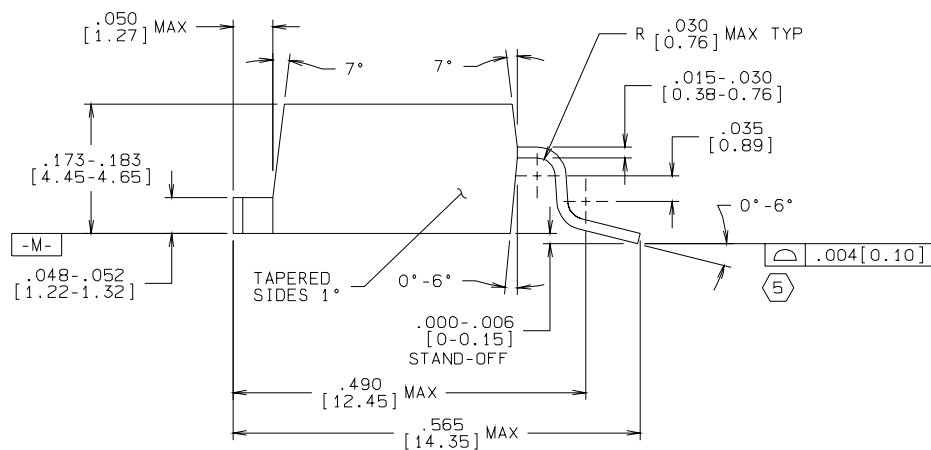
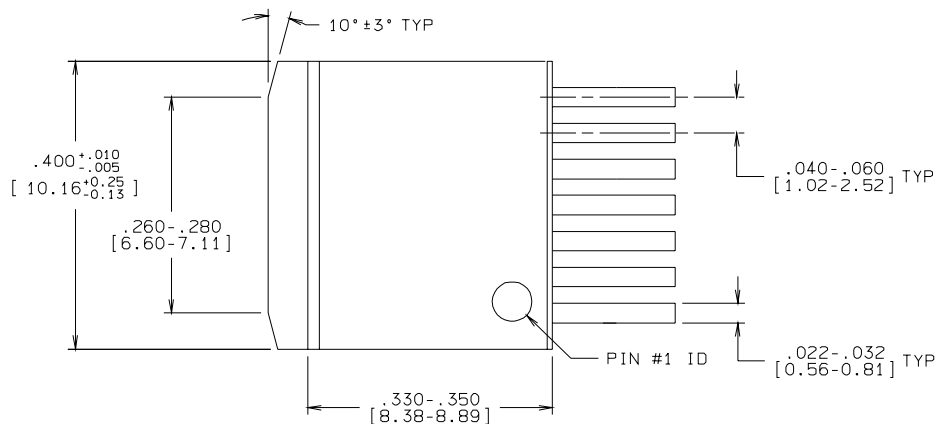




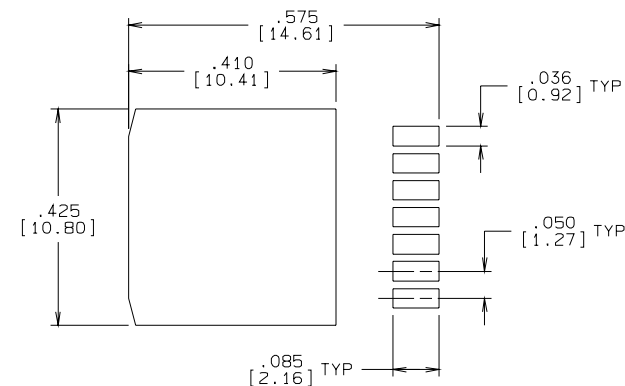
CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

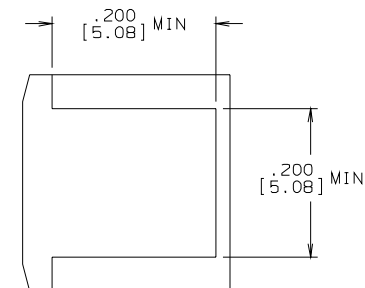
- STANDARD LEAD FINISH:
200 MICROINCHES / 5.08 MICROMETERS MINIMUM LEAD/TIN
15/85 ON OLIN 194 COPPER OR EQUIVALENT.
- MAXIMUM VERTICAL BURR ON HEATSINK NOT TO EXCEED
.003 IN/ 0.08 mm.
- NO PACKAGE CHIPS, CRACKS OR SURFACE INDENTATION ALLOWED
AFTER FORMING.
- JEDEC IS IN PROGRESS FOR BALLOT #10-340 AS OF 6/16/93.

5 UNDER ALL CONDITIONS, LEAD(S) MUST NOT BE ABOVE DATUM -M-
AND NO LEADS MAY BE LOWER THAN .006 IN/ 0.15 mm MEASURED FROM
DATUM -M- TO THE BOTTOM OF THE LEADS.

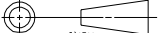
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09835	06/21/93	DEG/FL
B	REVISE LEADS: ADD $0^\circ-6^\circ$.000-.006 STAND-OFF & NOTE 5	10155	12/02/93	TL/KHT
C	BACK VIEW: .200 [5.08] MIN WAS .250 [6.35] MIN; NOTE 2: 0.08mm WAS 0.09mm.	10774	01/10/95	MS/



LEAD POSITION OVERLAY



BACK VIEW

APPROVALS		DATE		 <i>National Semiconductor</i> 2900 Semiconductor dr, Santa Clara, CA 95052-8090 TO-263, MOLDED, 7 LEAD, SURFACE MOUNT			
DRAWN		D.E. GRADY					
DFTG. CHK.		06/21/93					
ENGR. CHK.							
 PROJECTION INCH (MM)				SCALE	SIZE	DRAWING NUMBER	REV
				N/A	C	MKT-TS7B	C
DO NOT SCALE DRAWING				SHEET 1 OF 1			